

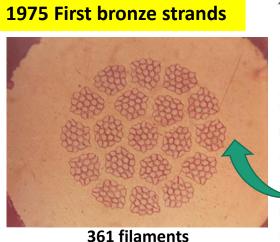


Design features and microstructure of the commercially produced high Jc internal tin Nb₃Sn strands with one common diffusion barrier

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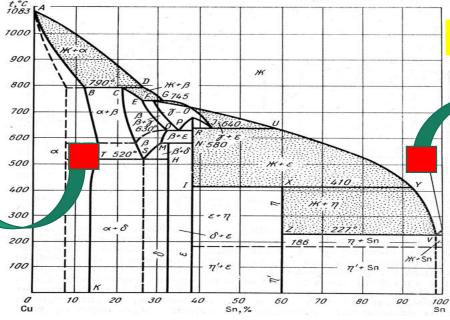
Nb₃Sn strands produced by bronze and internal tin methods

(In Russia: Development - Bochvar Institute; Production – [UMZ plant] - ChMZ plant)

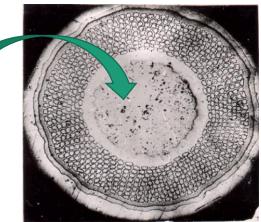


omnonents:

2 Components: Nb + Bronze (Cu-Sn)

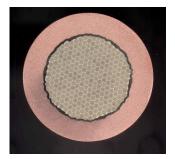


1975 First Internal Tin strands

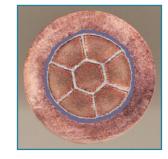


650 filaments 3 Components: Nb + Cu + Sn

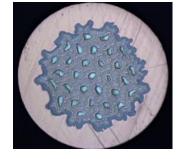
ChMZ plant, Glazov, 2009-2015



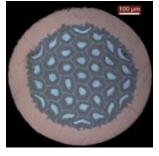
Bronze ITER type Nb₃Sn wire Jc = 850 A/mm²



IT ITER type Nb₃Sn wireJ c = 1000 A/mm²

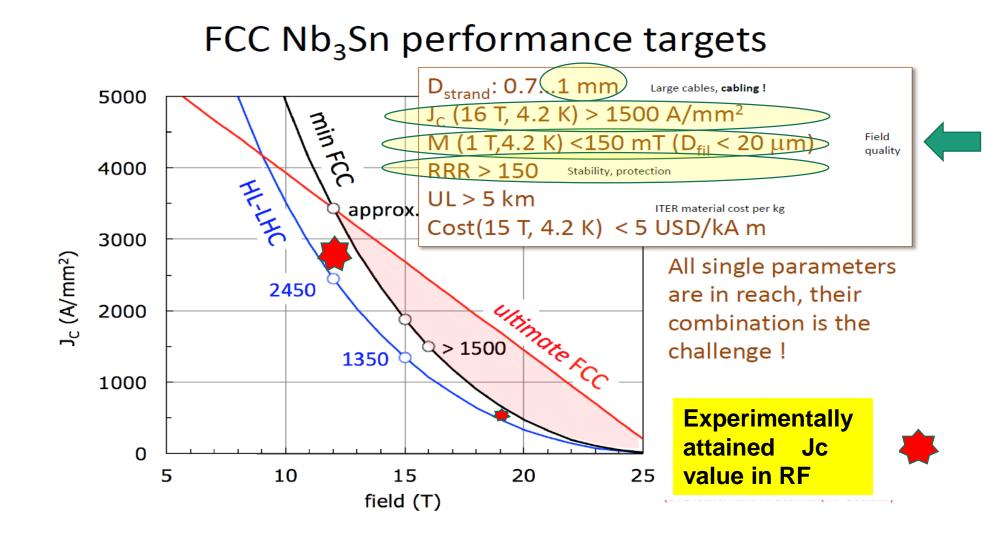






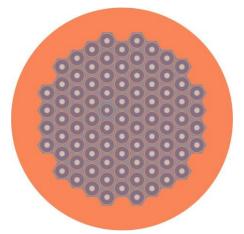
IT LHC-FCC type Nb₃Sn wires with common and separated barriers Jc (non Cu; 12 T) up to 2500 A/mm²





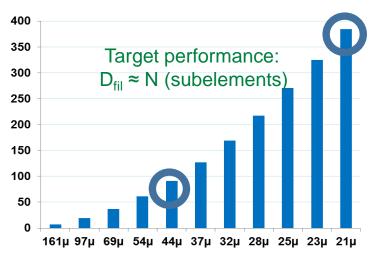


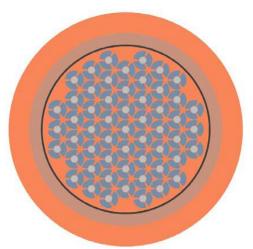




Separated diffusion barriers around each subelements

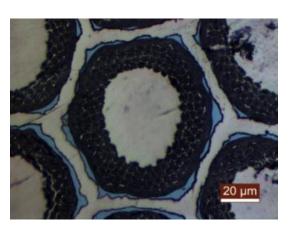
85 monoelements Deff in the order of **50 μm**





Single common diffusion barrier

55 splitted sub-elements (equavalent to 270 effective filaments) Deff in the order of **25 μm**



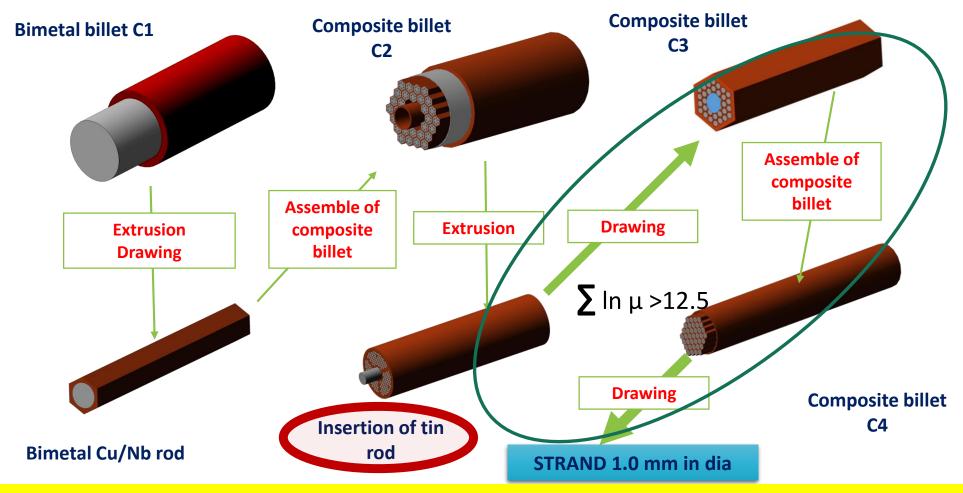
Up to 32% of non Cu area will be occupied by unreacted Nb for 20 µm subelements (assuming 4 µm average thickness)

- Increase of the number of subelements leads to the corresponding increase of the technological drawbacks connected with the large free surface between subelements enhancement and large preliminary plastic deformation before assembling of the final billet
- Difficult to maintain initial RRR >150 for strands with separated diffusion barriers around each subelements





Internal tin strand production scheme



Particular feature of IT strands – large cold plastic deformation by drawing without intermediate heat treatments (problems – formation of metallurgical bonding; texture formation)





Basic design parameters of IT strands with one common diffusion barrier designed for HI-LU specifications

Parameter	Common Ta barrier
Strand diameter, mm	0.7
Cu/non Cu	1,20
Nb fraction within barrier, % vol.	≈41 %
Nb ₃ Sn fraction in non Cu area after HT, %vol.	46 %
D subelement, µm	70.5
Subelement spacing, µm	2.68
D filament, μm	2.7
Cu thickness between Nb filaments, µm	0.3
Ti doping (artificial; in Nb filaments), at%	1.74

The artificial doping by Ti has been done by insertion of the plurality of NbTi rods in the Nb filaments

(FEC hh ee he

Deformation of IT strand's components without intermediate heat treatments





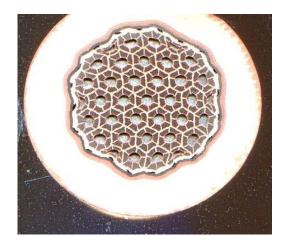
	Common barrier	Distributed barriers
Nb inside subelements	InAo/A = 11-12	InAo/A = 11-12
Nb (Ta) in diffusion barrier	InAo/A = 8 - 9	InAo/A = 11-12



60 mm in dia Composite outer tube consists of stabilizing Cu, strengthening Cu-Nb layer, Nb difusion barrier, Ta dividing inserts, technological Cu



Hexagonal composite rod (subelement)consists of axial Sn alloy rod, 6 sectors composed by the Nb(Ti) doped filaments embedded into Cu matrix and separated by the Cu layers

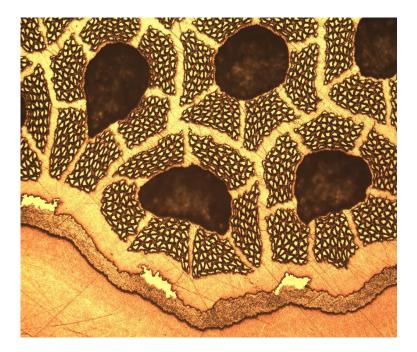


2 mm in dia final design composite wire consists of 37 subelements 37 tin sources, 222 Cu-Nb sectors

Different stages of IT strand manufacture

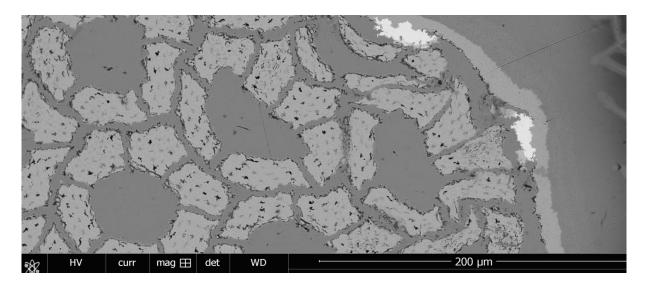


(Design of Diffusion barrier optimization)



The Nb barrier should be optimized with 20 Ta rods for subdividing the circular Nb₃Sn layer. The thikness could be deminished due to positive role of Cu-Nb strengthening layer adjucent to Nb barrier.

The preliminary design assumes the thickness of Nb barrier around 8 μ m The 4-5 μ m of Nb barrier should be reacted with the formation of the Nb3Sn phase. The vokume fraction of diffusion batrrier will be around 2,5% from non-Cu area.



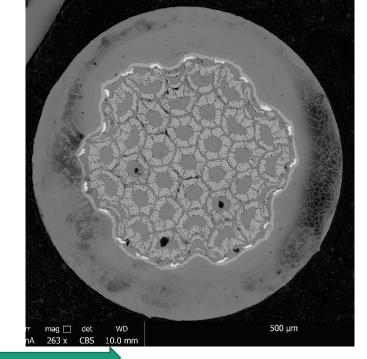
The strand after reaction heat treatment with several intermediate stages 220 C + 370 + 570 C + (660-700 C)

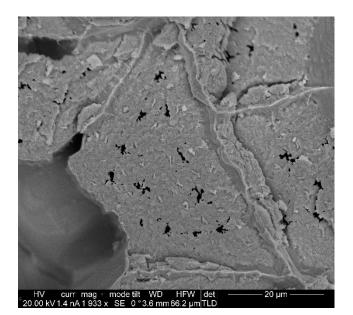


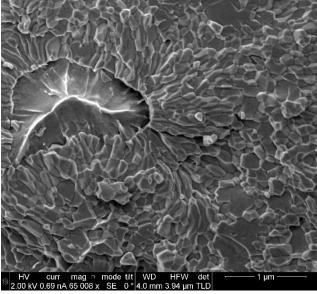
The microstructure of IT strands (common barrier)

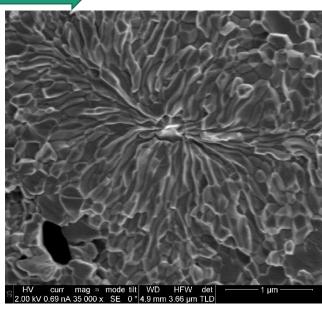
The microstructure of Nb3Sn layers in highly bridged macrofilaments has to be optimized in the futher R&D

Increase of last stage heat treatment's(660 C) duration акщь 25 р ещ 100 р





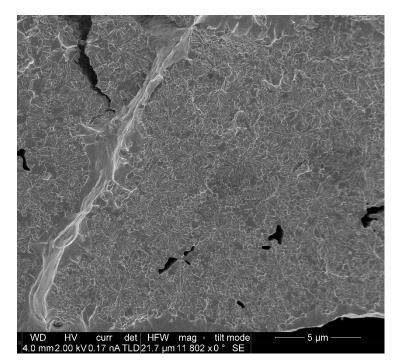


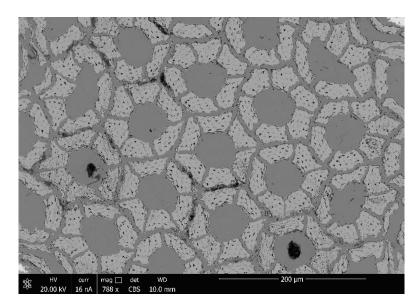


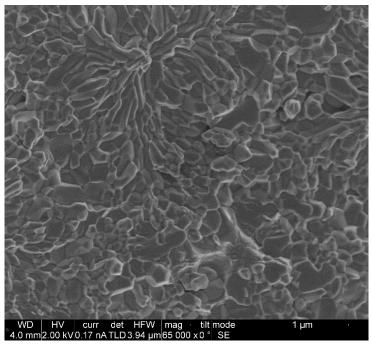


The microstructure of IT strands (common barrier)

Each sector of Nb filaments forms a macrofilament as a result of reaction of Nb and Sn with formation of Nb3Sn phase (last stage heat treatment temperature – 700 C)

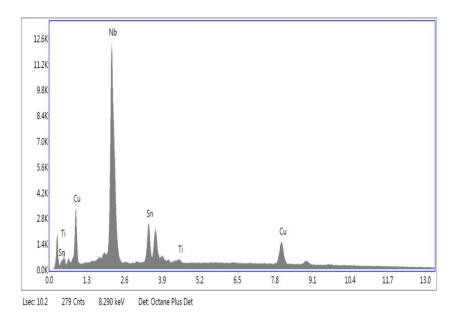


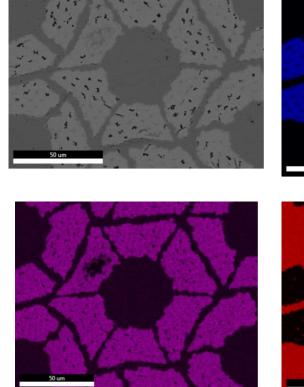


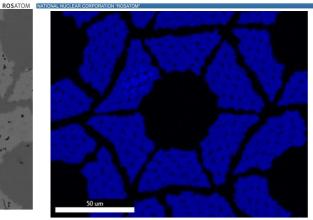




The microstructure of IT strands (common barrier)







FUEL COMPANY OF ROSATOM

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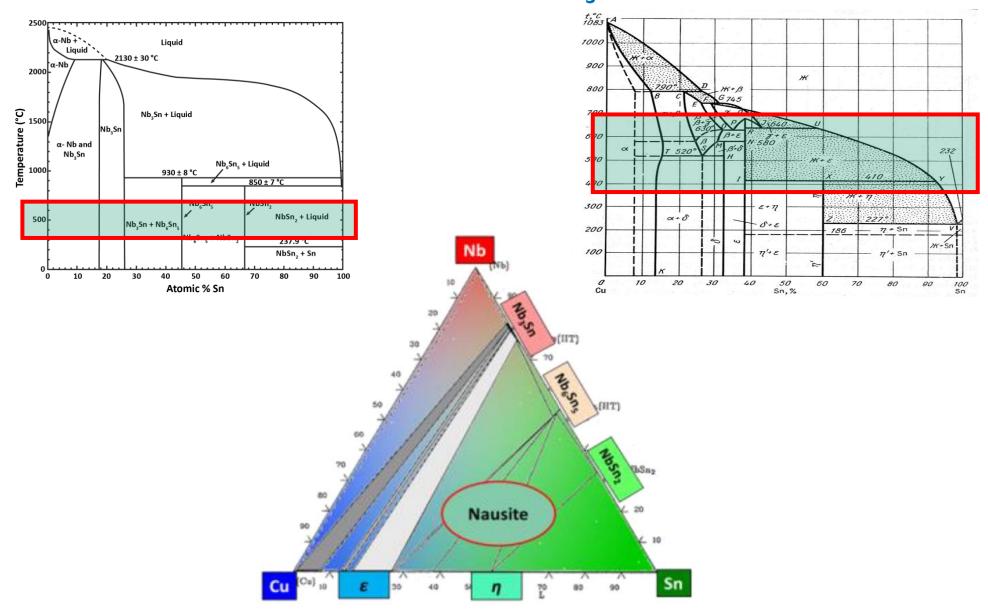
Nb

		IN	N		
				-	
~	Jes-		-{		30
				4	
s	0 um	1	C		
			Cu		

						Sn				Сι
Element	Weight %	Atomic %	Net Int.	Error %	Kratio	Z	R	А	F	
NbL	57.59	53.56	11448.70	2.98	0.4988	0.9949	1.0122	0.8614	1.0107	
SnL	18.26	13.29	2223.70	5.05	0.1426	0.9315	1.0575	0.8216	1.0210	
TiK	0.65	1.18	144.90	22.30	0.0059	1.1160	0.9083	0.7848	1.0297	
CuK 10.0	23.50 04.2018	31.96	2300.60	3.70 FCC	0.2644 week 2018 -	1.0785 Amsterdam	0.9587	0.9615	1.0848	



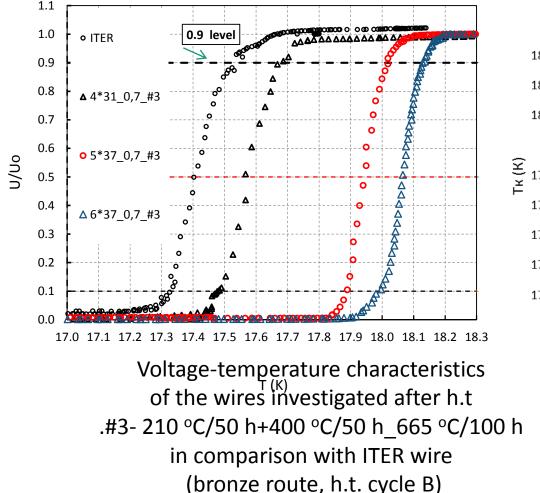
Heat treatment of Internal Tin Nb₃Sn Strands

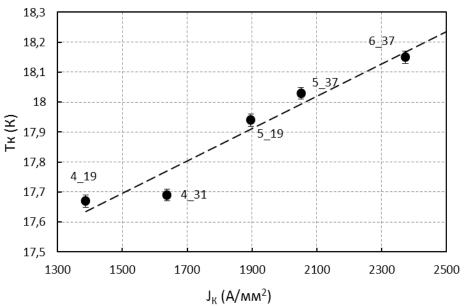






Superconducting properties of IT strands Tc - Jc



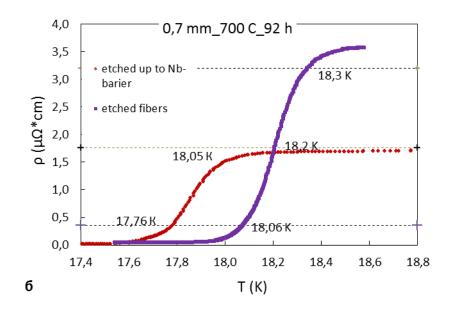


Critical temperature of IT strands are higher than of bronze processed





Superconducting properties of IT strands



y = -4.3893x + 121.28 $R^2 = 0.9997$ Jc1/2B1/4 Поле, Тл

Kramer plot

Etching out outr Cu and outer diffusion barrier led to increase of the Tc caused by the relaxation of the internal stresses





SUMMARY

- The separation of the Nb filaments inside the subelements could be effectively realized by the introduction of the layers of copper based plates.
- The formation of Nb3Sn "macrofilaments" with complete reaction of Nb filaments has been observed
- Nonuniformity of the grains microstructure in the Nb3Sn "macrofilaments" has been found with columnar grains that is characteristic for solid state reaction altogether with the large equaxed grains in the boundaries regions between former Nb filaments
- The optimization of the heat treatment regimes with the accent on the intermediate 570 C stage is in progress.
- The attainment of the FCC strand's specifications is challenging, still requires intensive R&D works but seems to be realistic